

**AMENDMENTS TO THE CLAIMS**

**Claims 1-12 (Canceled)**

*Entered by 4/25/05*

**Claim 13 (Currently Amended)** An apparatus for plating a substrate by immersing the substrate in baths containing plating solutions, the substrate proceeding along a predetermined process path within the apparatus, and the substrate having a surface with fine pits formed thereon, the apparatus comprising:

a first bath containing a first plating solution and being adapted to form a first plating layer within the fine pits;

a second bath disposed after the first bath in the process path and containing a second plating solution different from the first plating solution, said second bath being adapted to form a second plating layer on the first plating layer;

a first washing station disposed between the first plating bath and the second plating bath in the process path;

a second washing station disposed after the second plating bath in the process path; and

a drying station disposed after the second washing station in the process path.

**Claim 14 (Original)** The apparatus of claim 13, further comprising:

a first pump in fluid contact with the first plating bath and a source of the first plating solution; and

a second pump in fluid contact with the second plating bath and a source of the second plating solution.

**Claim 15 (Previously Presented)** The apparatus of claim 13, further comprising:

a preprocessing bath disposed before the first bath in the process path and containing an aqueous sulfuric acid solution; and

a third washing station between the preprocessing bath and the first bath in the processing path.